

# EUROPEAN PATENT OFFICE

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TITLE : RESIN COMPOSITION

ABSTRACT : PROBLEM TO BE SOLVED: To provide a resin composition which can cover a substrate to give a coating film having a high grade and high strength without blisters in the coating film on heating and drying the coating film in a processing process, when used as a coating.

SOLUTION: This resin composition comprising an aqueous resin dispersion having a solid content concentration of  $\geq 50$  wt.% and an organopolysiloxane polyoxyalkylene glycol is characterized in that the molar ratio of the hydrogen atoms of the alkyl groups of the organopolysiloxane to the hydrogen atoms of the polyoxyalkylene glycol chain is 5/95 to 50/50 and that the polyoxyalkylene glycol chain is obtained from ethylene oxide and an alkylene oxide except the ethylene oxide.

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